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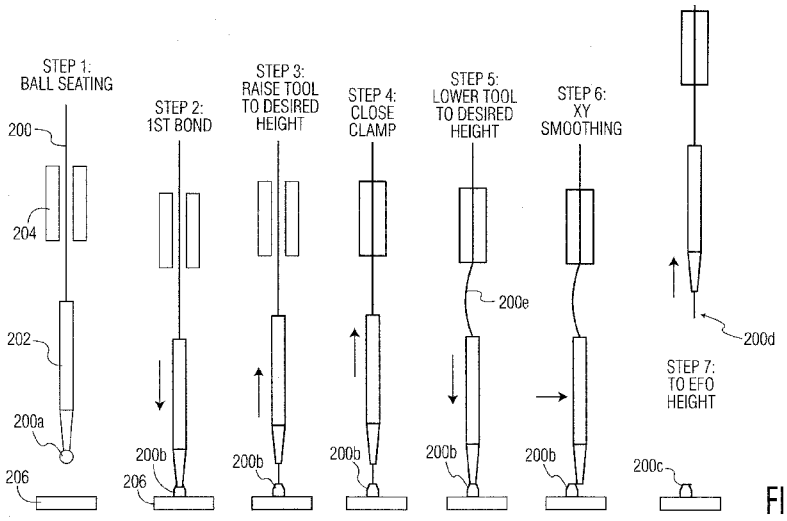


FIG. 2

(57) Abstract: A method of forming a conductive bump is provided. The method includes the steps of: (1) bonding a free air ball to a bonding location using a bonding tool to form a bonded ball; (2) raising the bonding tool to a desired height, with a wire clamp open, while paying out wire continuous with the bonded ball; (3) closing the wire clamp; (4) lowering the bonding tool to a smoothing height with the wire clamp still closed; (5) smoothing an upper surface of the bonded ball, with the wire clamp still closed, using the bonding tool; and (6) raising the bonding tool, with the wire clamp still closed, to separate the bonded ball from wire engaged with the bonding tool.

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